



Material Content Data Sheet



Sales Product Name		SAF-C165-LM HA		Issued		4. July 2019		
MA#		MA001192860						
Package		PG-MQFP-100-2		Weight*		1787.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.388	0.97	0.97	9730	9730
leadframe	non noble metal	magnesium	7439-95-4	0.538	0.03		301	
	inorganic material	silicon	7440-21-3	2.331	0.13		1304	
	non noble metal	nickel	7440-02-0	10.756	0.60		6019	
	non noble metal	copper	7440-50-8	344.917	19.30	20.06	193007	200631
wire	noble metal	gold	7440-57-5	3.585	0.20	0.20	2006	2006
encapsulation	organic material	carbon black	1333-86-4	6.911	0.39		3867	
	plastics	epoxy resin	-	200.406	11.21		112142	
	inorganic material	silicondioxide	60676-86-0	1174.795	65.75	77.35	657387	773396
leadfinish	non noble metal	tin	7440-31-5	19.520	1.09	1.09	10923	10923
plating	noble metal	silver	7440-22-4	1.857	0.10	0.10	1039	1039
glue	plastics	epoxy resin	-	1.016	0.06		569	
	noble metal	silver	7440-22-4	3.048	0.17	0.23	1706	2275
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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